



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ22DN20NS3 G		<b>Issued</b>		22. July 2019		
<b>MA#</b>		MA004242854						
<b>Package</b>		PG-TSDSON-8-37		<b>Weight*</b>		35.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.454	1.27	1.27	12726	12726
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		99	
	non noble metal	zinc	7440-66-6	0.014	0.04		397	
	non noble metal	iron	7439-89-6	0.283	0.79		7943	
wire	non noble metal	copper	7440-50-8	11.505	32.25	33.09	322518	330957
	noble metal	gold	7440-57-5	0.035	0.10	0.10	989	989
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1068
plastics	plastics	epoxy resin	-	1.962	5.50		54992	
	inorganic material	silicondioxide	60676-86-0	17.046	47.79	53.40	477843	533903
	leadfinish	non noble metal	tin	7440-31-5	0.370	1.04	1.04	10374
plating	noble metal	silver	7440-22-4	0.081	0.23	0.23	2265	2265
solder	non noble metal	tin	7440-31-5	0.012	0.03		345	
	noble metal	silver	7440-22-4	0.015	0.04		431	
	non noble metal	lead	7439-92-1	0.588	1.65	1.72	16480	17256
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		110	
	non noble metal	iron	7439-89-6	0.078	0.22		2197	
	non noble metal	copper	7440-50-8	3.182	8.92	9.15	89196	91530
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com